

**14A, 100V, 0.160 Ohm, N-Channel Power MOSFETs**

These are N-Channel enhancement mode silicon gate power field effect transistors. They are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching convertors, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA17411.

**Ordering Information**

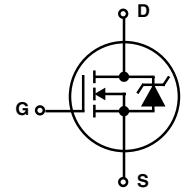
PART NUMBER	PACKAGE	BRAND
RF1S530SM	TO-263AB	RF1S530

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-263AB variant in the tape and reel, i.e., RF1S530SM9A.

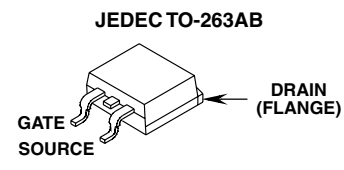
**Features**

- 14A, 100V
- $r_{DS(ON)} = 0.160\Omega$
- Single Pulse Avalanche Energy Rated
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

**Symbol**



**Packaging**



**Absolute Maximum Ratings**  $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

	RF1S530SM	UNITS
Drain to Source Breakdown Voltage (Note 1)	100	V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1)	100	V
Continuous Drain Current	14	A
$T_C = 100^\circ\text{C}$	10	A
Pulsed Drain Current (Note 3)	56	A
Gate to Source Voltage	$\pm 20$	V
Maximum Power Dissipation	79	W
Dissipation Derating Factor	0.53	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy Rating (Note 4)	69	mJ
Operating and Storage Temperature	-55 to 175	$^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	300	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334	260	$^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

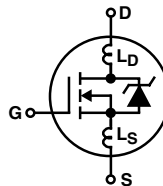
NOTE:

1.  $T_J = 25^\circ\text{C}$  to  $150^\circ\text{C}$ .

## RF1S530SM

### Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 10)	100	-	-	V	
Gate to Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$	2	-	4.0	V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 95\text{V}$ , $V_{GS} = 0\text{V}$	-	-	25	$\mu\text{A}$	
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ , $V_{GS} = 0\text{V}$ , $T_J = 150^\circ\text{C}$	-	-	250	$\mu\text{A}$	
On-State Drain Current (Note 2)	$I_{D(ON)}$	$V_{DS} > I_{D(ON)} \times r_{DS(ON)}$ MAX, $V_{GS} = 10\text{V}$	14	-	-	A	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 500$	nA	
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = 8.3\text{A}$ , $V_{GS} = 10\text{V}$ (Figures 8, 9)	-	0.14	0.16	$\Omega$	
Forward Transconductance (Note 2)	$g_{fs}$	$V_{DS} \geq 50\text{V}$ , $I_D = 8.3\text{A}$ (Figure 12)	5.1	7.6	-	S	
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} = 50\text{V}$ , $I_D \approx 14\text{A}$ , $R_G \approx 12\Omega$ , $R_L = 3.4\Omega$ MOSFET Switching Times are Essentially Independent of Operating Temperature	-	12	15	ns	
Rise Time	$t_r$		-	35	65	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	25	70	ns	
Fall Time	$t_f$		-	25	59	ns	
Total Gate Charge (Gate to Source + Gate to Drain)	$Q_{g(TOT)}$	$V_{GS} = 10\text{V}$ , $I_D = 14\text{A}$ , $V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ $I_{g(REF)} = 1.5\text{mA}$ (Figure 14)	-	18	30	nC	
Gate to Source Charge	$Q_{gs}$	Gate Charge is Essentially Independent of Operating Temperature	-	4	-	nC	
Gate to Drain "Miller" Charge	$Q_{gd}$		-	7	-	nC	
Input Capacitance	$C_{ISS}$	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$ (Figure 11)	-	600	-	pF	
Output Capacitance	$C_{OSS}$		-	250	-	pF	
Reverse Transfer Capacitance	$C_{RSS}$		-	50	-	pF	
Internal Drain Inductance	$L_D$	Measured from the Contact Screw on Tab To Center of Die	Modified MOSFET Symbol Showing the Internal Devices Inductances	-	3.5	-	nH
		Measured from the Drain Lead, 6mm (0.25in) from Package to Center of Die		-	4.5	-	nH
Internal Source Inductance	$L_S$	Measured from the Source Lead, 6mm (0.25in) From Header to Source Bonding Pad		-	7.5	-	nH
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	1.9	$^\circ\text{C/W}$	
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	Free Air Operation	-	-	62.5	$^\circ\text{C/W}$	
	$R_{\theta JA}$	RF1S540SM Mounted on FR-4 Board with Minimum Mounting Pad	-	-	62	$^\circ\text{C/W}$	



### Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	$I_{SD}$	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Diode	-	-	14	A
Pulse Source to Drain Current (Note 2)	$I_{SDM}$		-	-	56	A
Source to Drain Diode Voltage (Note 2)	$V_{SD}$	$T_J = 25^\circ\text{C}$ , $I_{SD} = 14\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 13)	-	-	2.5	V
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}$ , $I_{SD} = 14\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	5.5	120	250	ns
Reverse Recovery Charge	$Q_{RR}$	$T_J = 25^\circ\text{C}$ , $I_{SD} = 14\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	0.17	0.6	1.3	$\mu\text{C}$

#### NOTES:

- Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Repetitive rating: pulse width limited by Max junction temperature. See Transient Thermal Impedance curve (Figure 3).
- $V_{DD} = 25\text{V}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 530\mu\text{H}$ ,  $R_G = 25\Omega$ , peak  $I_{AS} = 14\text{A}$  (Figures 15, 16).

**Typical Performance Curves** Unless Otherwise Specified

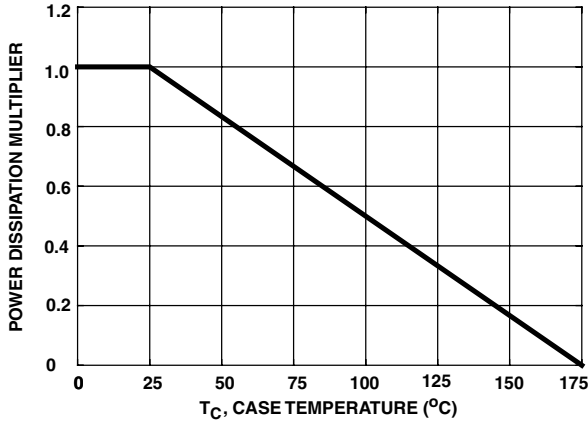


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

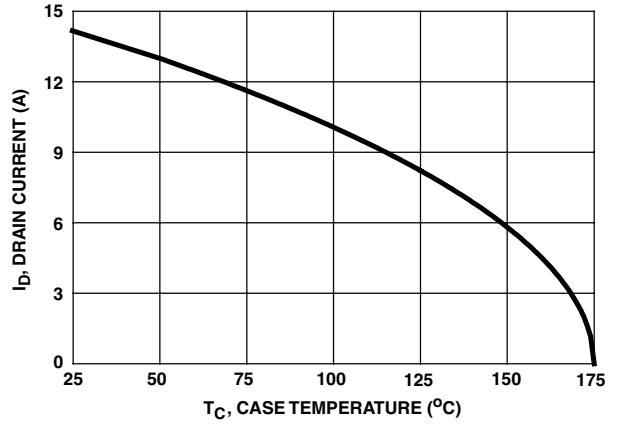


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

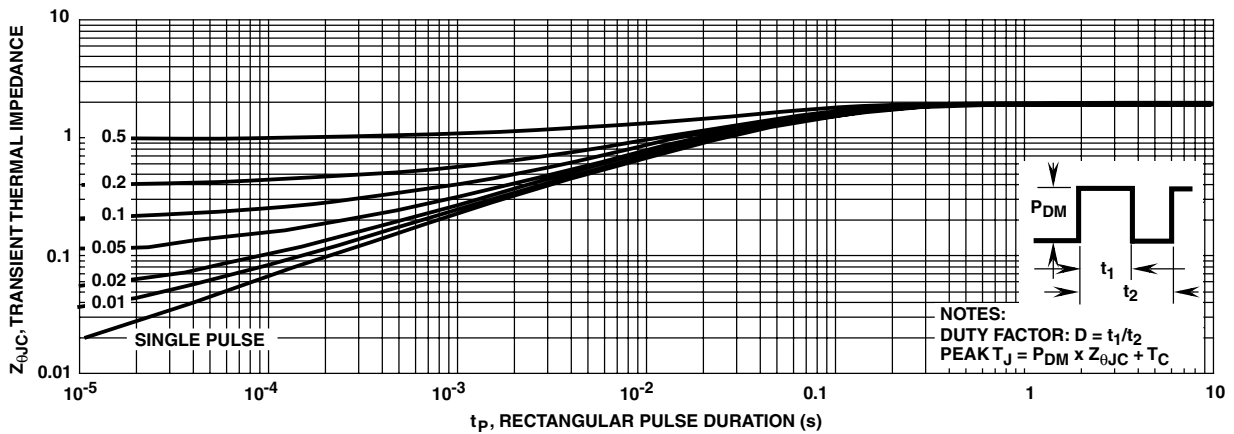


FIGURE 3. MAXIMUM TRANSIENT THERMAL IMPEDANCE

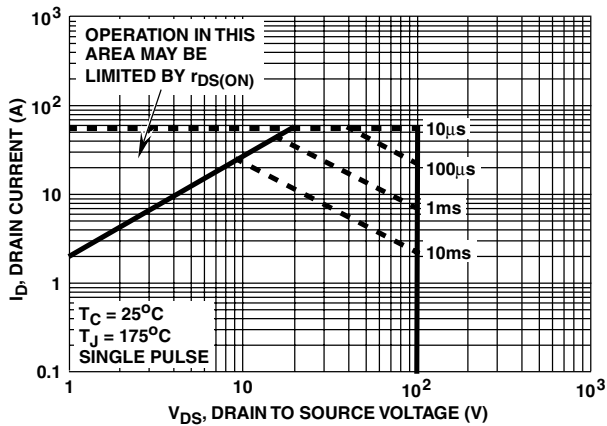


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

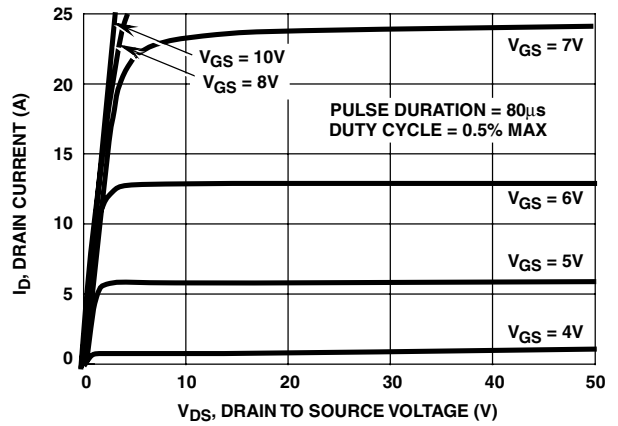


FIGURE 5. OUTPUT CHARACTERISTICS

Typical Performance Curves Unless Otherwise Specified (Continued)

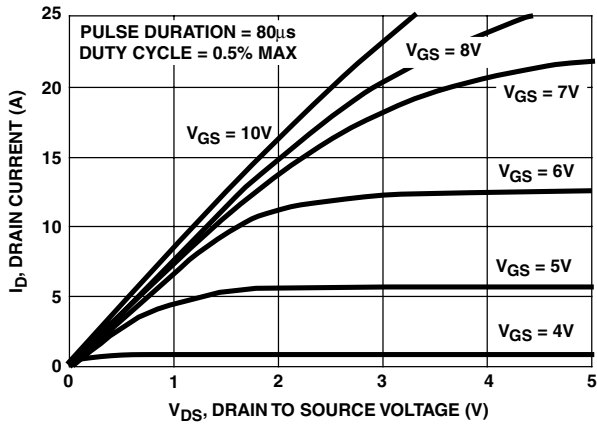


FIGURE 6. SATURATION CHARACTERISTICS

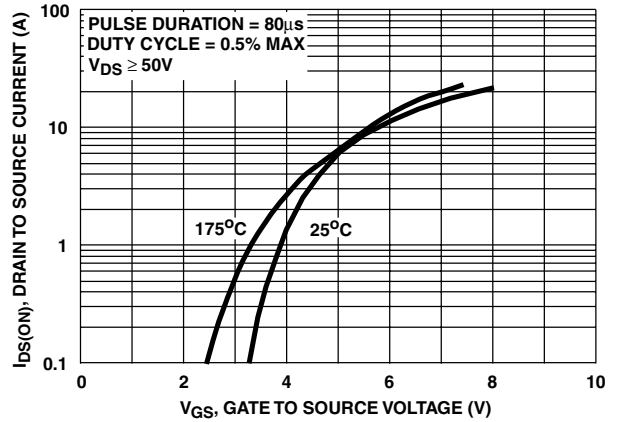


FIGURE 7. TRANSFER CHARACTERISTICS

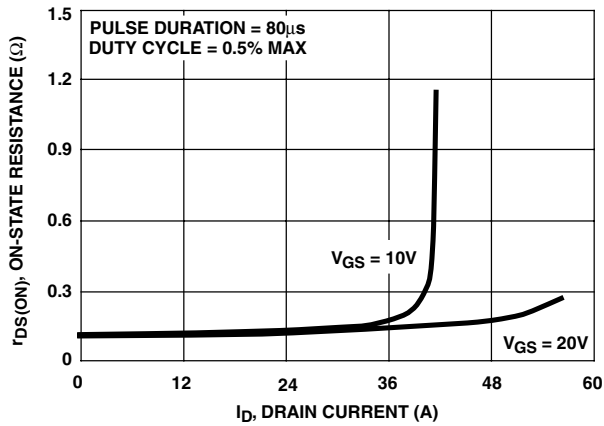


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

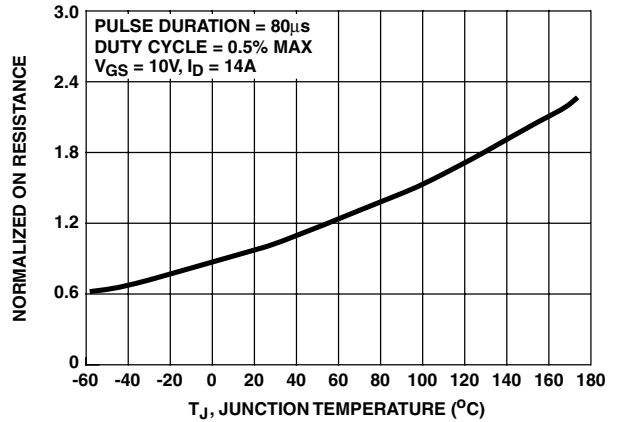


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

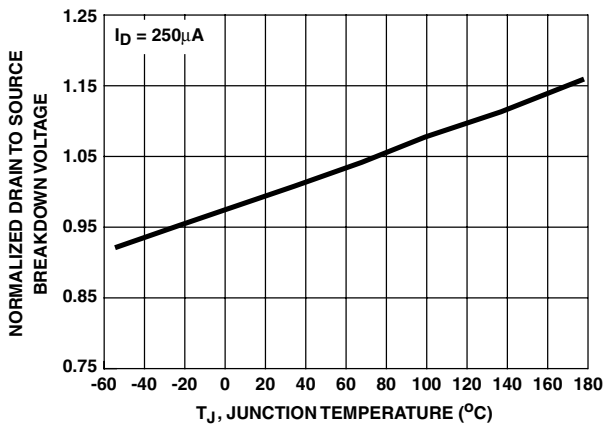


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

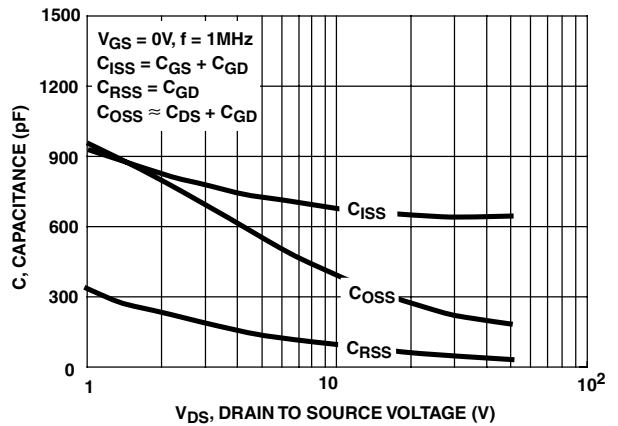


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

Typical Performance Curves Unless Otherwise Specified (Continued)

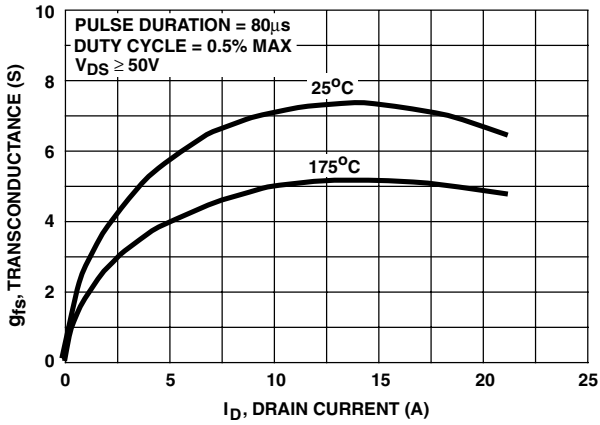


FIGURE 12. TRANSCONDUCTANCE vs DRAIN CURRENT

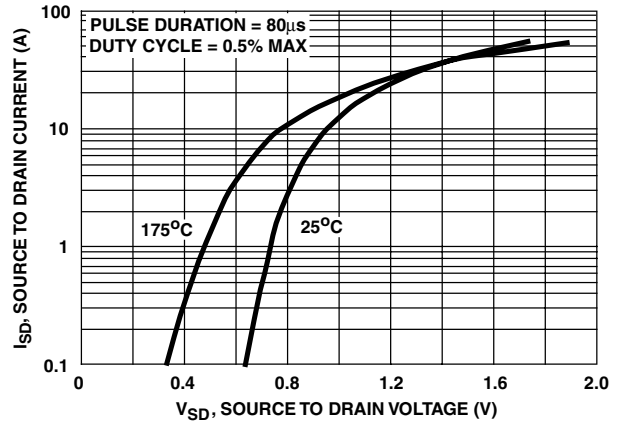


FIGURE 13. SOURCE TO DRAIN DIODE VOLTAGE

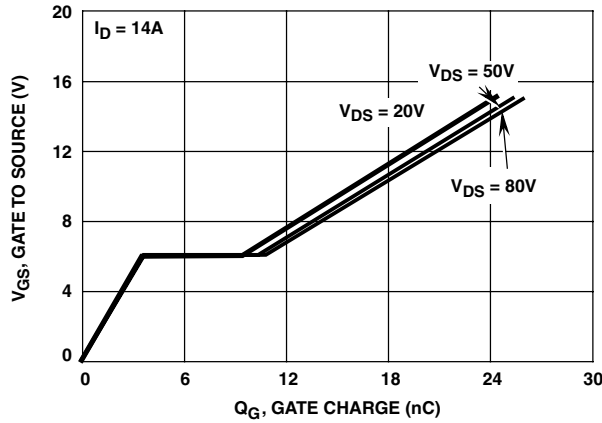


FIGURE 14. GATE TO SOURCE VOLTAGE vs GATE CHARGE

Test Circuits and Waveforms

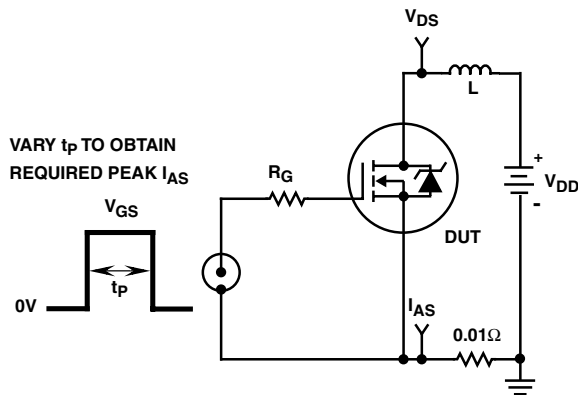


FIGURE 15. UNCLAMPED ENERGY TEST CIRCUIT

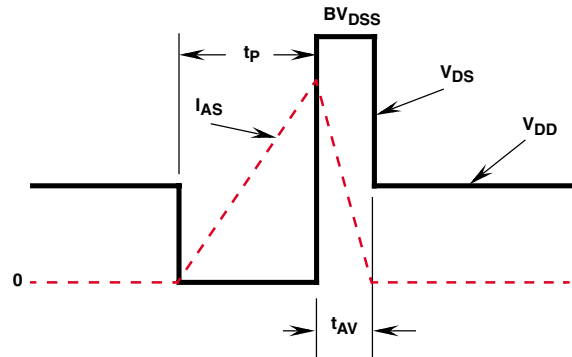


FIGURE 16. UNCLAMPED ENERGY WAVEFORMS

Test Circuits and Waveforms (Continued)

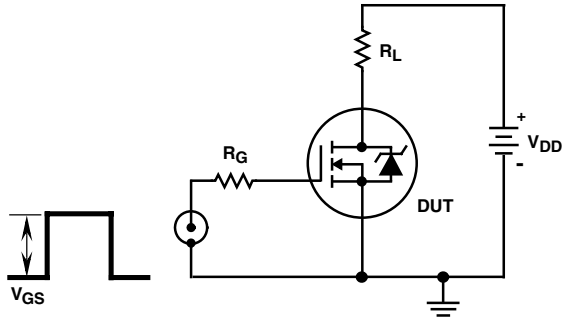


FIGURE 17. SWITCHING TIME TEST CIRCUIT

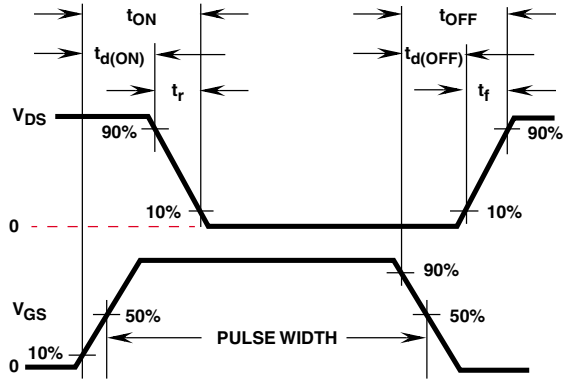


FIGURE 18. RESISTIVE SWITCHING WAVEFORMS

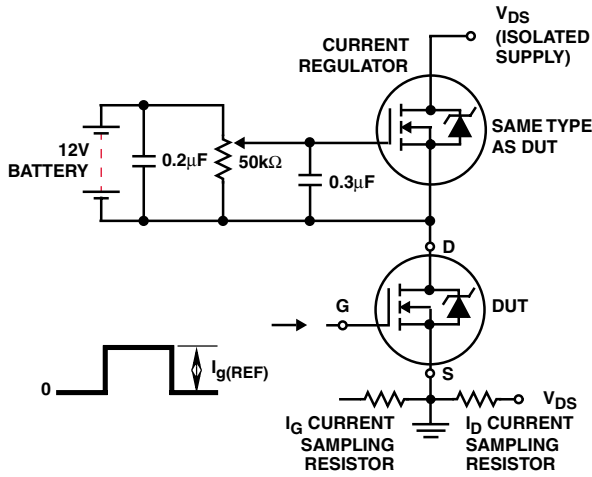


FIGURE 19. GATE CHARGE TEST CIRCUIT

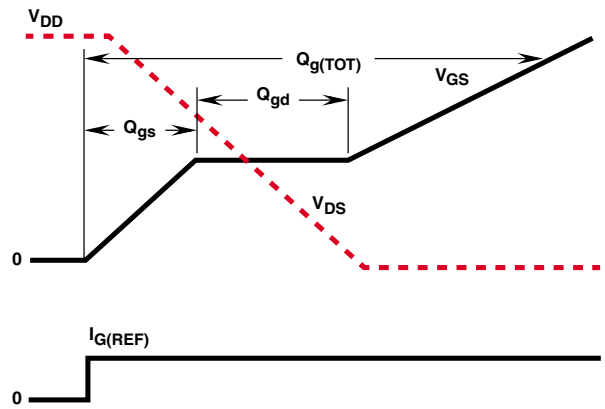


FIGURE 20. GATE CHARGE WAVEFORMS

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Bottomless <sup>TM</sup>	FAST <sub>r</sub> <sup>TM</sup>	POP <sup>TM</sup>	SuperSOT <sup>TM</sup> -6
CoolFET <sup>TM</sup>	GlobalOptoisolator <sup>TM</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>TM</sup> -8
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Datasheet Identification	Product Status	Definition
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